

STATEMENT UNDER 37 CFR 3.73(b)Applicant/Patent Owner: Matsushita Electric Industrial Co., Ltd.Application No./Patent No: 6,441,420 Filed/Issue Date: August 27, 2002Entitled: SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAMEMatsushita Electric Industrial Co., Ltd., a Corporation

(Name of Assignee)

(Type of Assignee, e.g., corporation, partnership, university, government agency, etc.)

states that it is:

1. ☒ the assignee of the entire right, title, and interest; or
2. ☐ an assignee of less than the entire right, title and interest.
The extent (by, percentage) of its ownership interest is _____%

in the patent application/patent identified above by virtue of either:

- A. ☒ An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the United States Patent and Trademark Office at Reel 010824, Frame 0256, or for which a copy thereof is attached.

OR

- B. ☐ A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as shown below:

1. From: _____ To: _____
The document was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached.
2. From: _____ To: _____
The document was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached.
3. From: _____ To: _____
The document was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached.

☐ Additional documents in the chain of title are listed on a supplemental sheet.

- ☐ Copies of assignments or other documents in the chain of title are attached.

[NOTE: A separate copy (i.e., the original assignment document or true copy of the original document) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the USPTO. See MPEP 302.08]

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.

March 15, 2004

Date

Isamu Shimura

Typed or printed name



Signature

Director, IP Development Center

Title

Burden Hour Statement: This form is estimated to take 0.2 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, Washington, DC 20231.

REISSUE APPLICATION DECLARATION BY THE INVENTOR

Docket Number: 740819-1052

As a below named inventor, I hereby declare that:

My residence, mailing address and citizenship are stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is described and claimed in patent number 6,441,420, granted August 27, 2002, and for which a reissue patent is sought on the invention entitled SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME, the specification of which

☒ is attached hereto.

☐ was filed on _____ as reissue application number _____ / _____
and was amended on _____
(If applicable)

I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.

I verily believe the original patent to be wholly or partly inoperative or invalid, for the reasons described below. (Check all boxes that apply.)

☐ by reason of a defective specification or drawing.

☒ by reason of the patentee claiming more or less than he had the right to claim in the patent.

☐ by reason of other errors.

At least one error upon which reissue is based is described below. If the reissue is a broadening reissue, such must be stated with an explanation as to the nature of the broadening:

Column 15, lines 11-12 "wherein an edge portion of the capacitor upper electrode is formed onto the protective insulating film;" should be deleted.

and

Column 15, line 19 "direct" before "connection" should be deleted.

(REISSUE APPLICATION DECLARATION BY THE INVENTOR, page 2)		Docket Number: 740819-1052	
<p>All errors corrected in this reissue application arose without any deceptive intention on the part of the applicant. As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the United States Patent and Trademark Office connected therewith.</p> <p>I/We hereby appoint:</p> <p>Practitioners at Customer Number 22204 as my/our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.</p> <p>Correspondence Address: Direct all communications about the application to:</p>			
<input checked="" type="checkbox"/> Customer Number	<div style="border: 1px solid black; display: inline-block; padding: 2px 10px;">22204</div> <i>Type Customer Number here</i>	→	<i>Place Customer Number Bar Code Label here</i>
<input type="checkbox"/> Firm or Individual Name			
Address			
Address			
City		State	Zip
Country			
Telephone		Fax	
<p>I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine and imprisonment, or both, under 18 U.S.C. 1001, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this declaration is directed.</p>			
Full name of sole or first inventor (given name, family name) Yoshihisa NAGANO			
Inventor's signature	 Date March 15, 2004		
Residence: Osaka, Japan	Citizenship: JAPAN		
Mailing Address: 3-26-1-203, Hara-cho, Suita-shi, Osaka 564-0004 JAPAN			
Full name of second joint inventor (given name, family name) Yasuhiro UEMOTO			
Inventor's signature	 Date March 15, 2004		
Residence: Shiga, Japan	Citizenship: JAPAN		
Mailing Address: 2-2-31, Nakanosho, Otsu-shi, Shiga 520-0837 JAPAN			
Full name of third joint inventor (given name, family name)			
Inventor's signature	Date		
Residence	Citizenship		
Mailing Address			
<input type="checkbox"/> Additional joint inventors are named on separately numbered sheets attached hereto.			